FIG.1

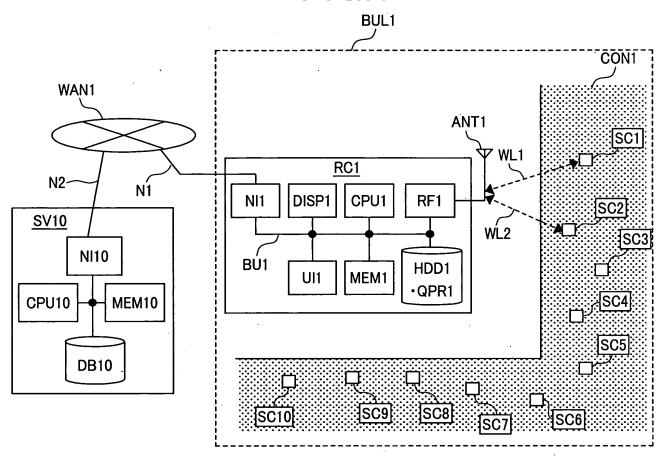
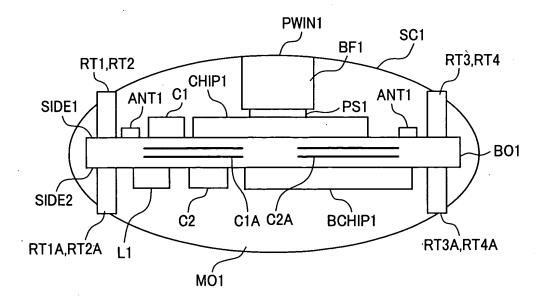
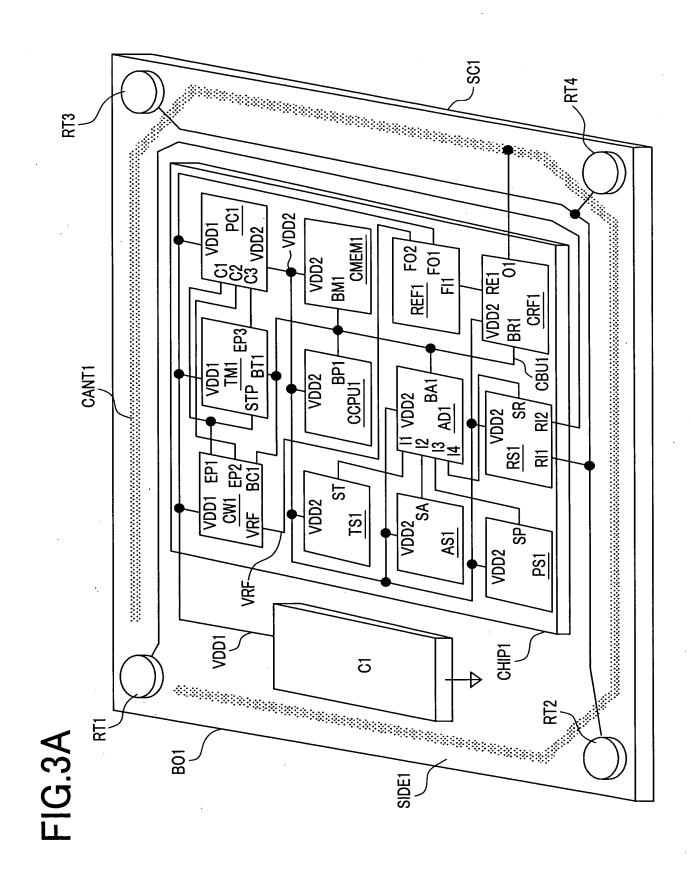


FIG.2





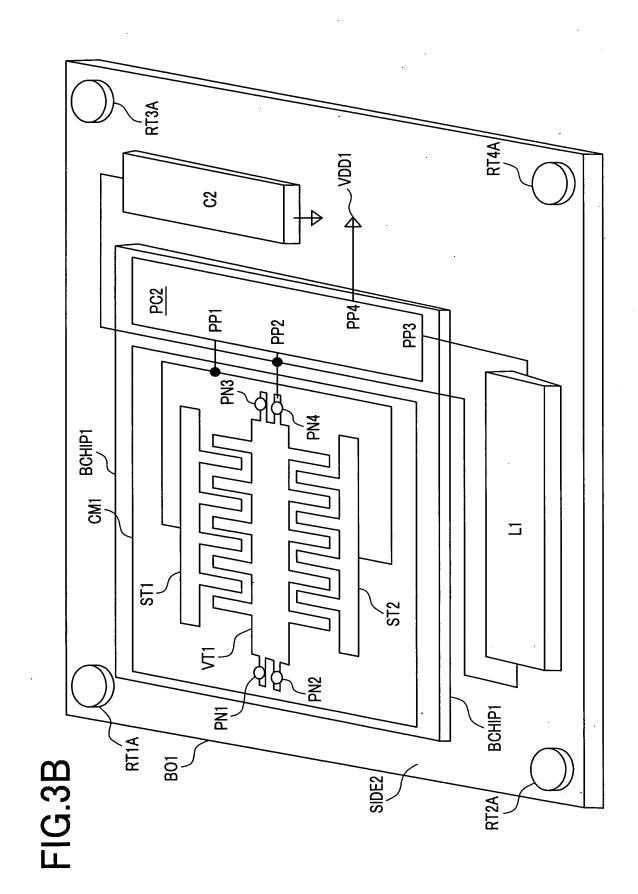


FIG.4

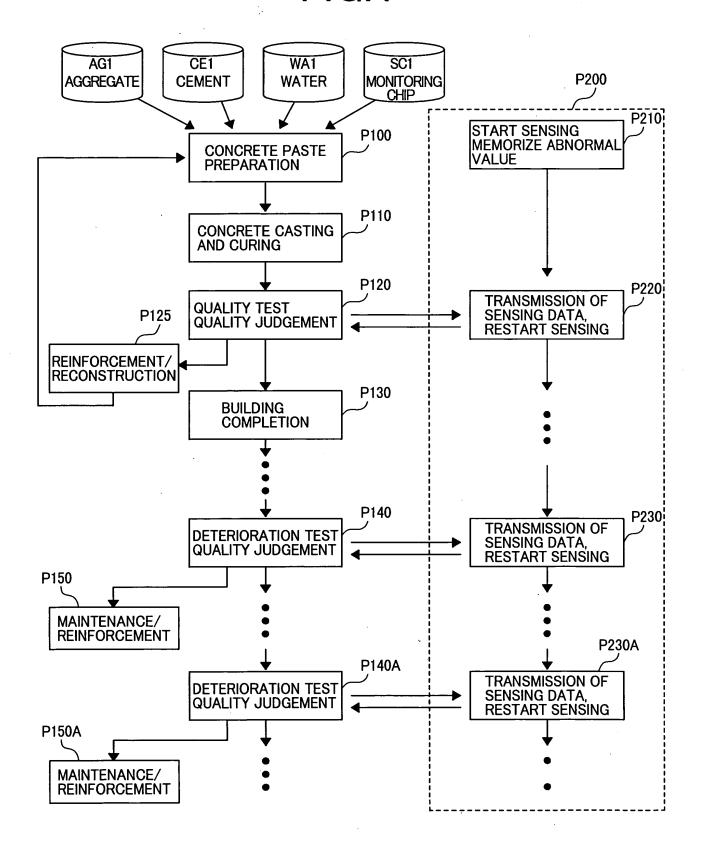


FIG.5A

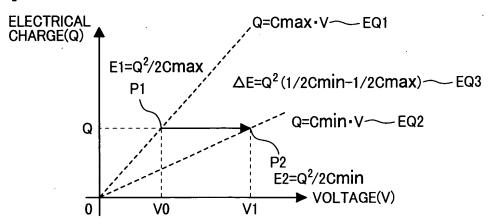


FIG.5B

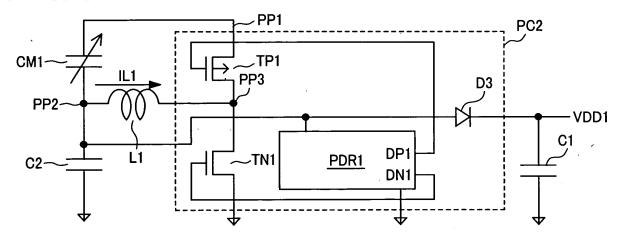
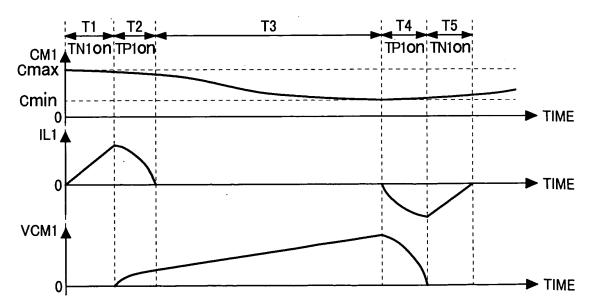
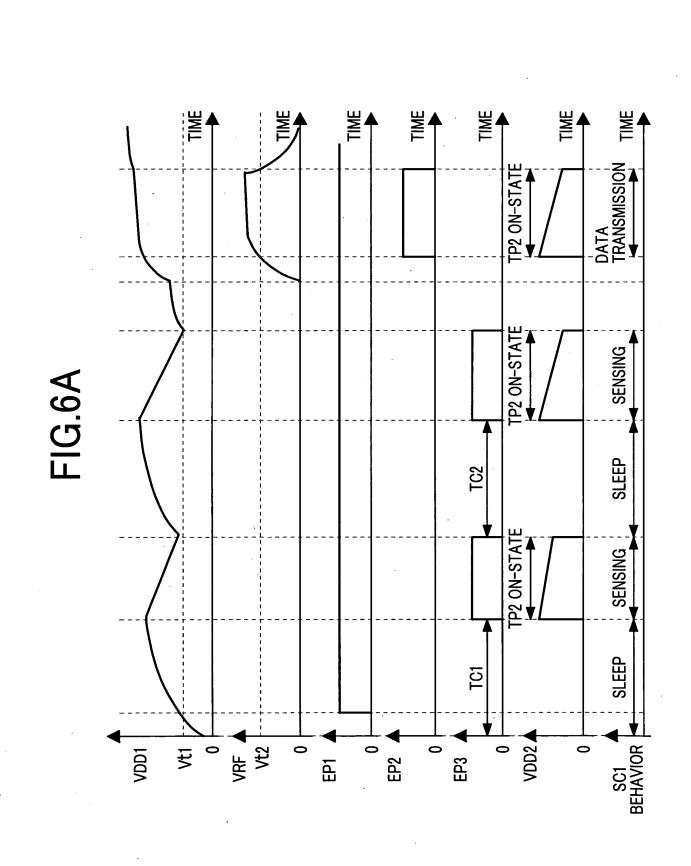


FIG.5C





STP EP3 I OIN CAREGO CAN RG1 8 SNT COUNT1 CBU1 CN REG1 RST1 PST1 PG3 CLK1 ~PG2 TIF1 B01 B02 FIG.6B 0801 BT1 ಬ ಶ \Im EP2 EP VDD1 -VDD1 S **VREF1** EI VC2 VC1 CWI1 BC1

VDD2

P.C.

FIG.7A

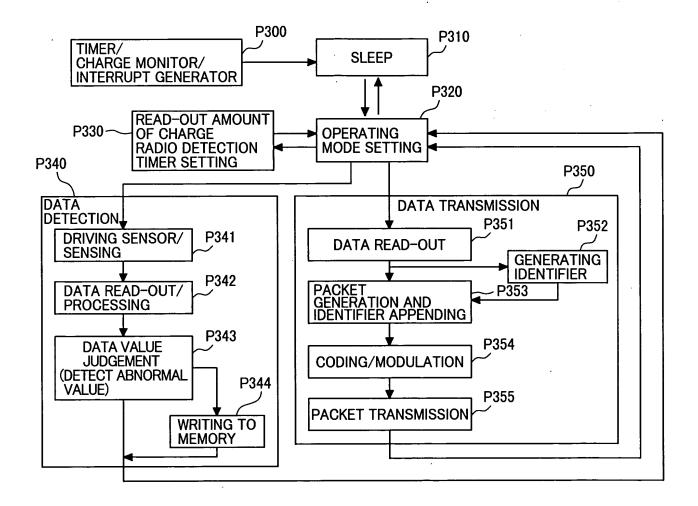
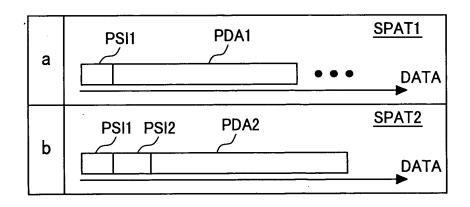


FIG.7B



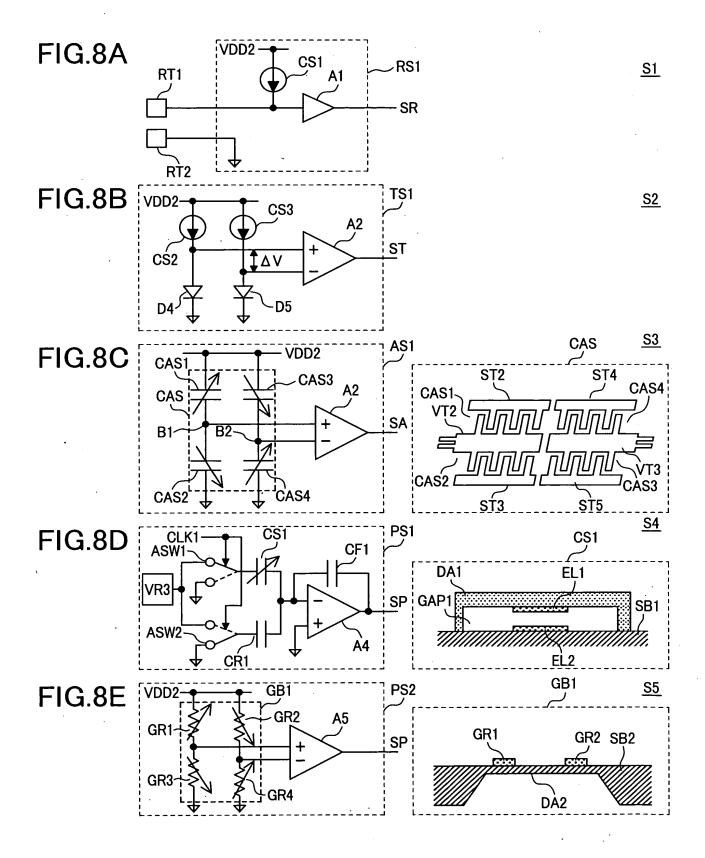


FIG.9

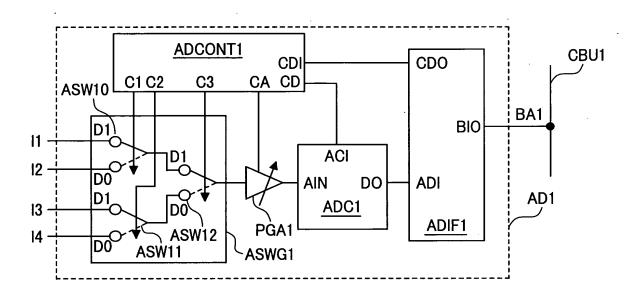
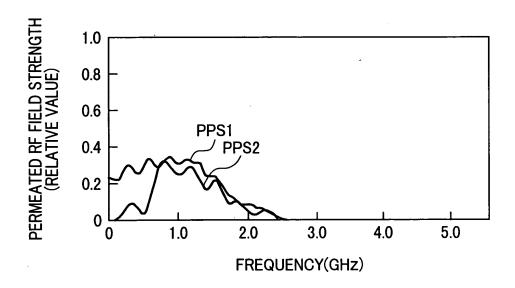


FIG.11



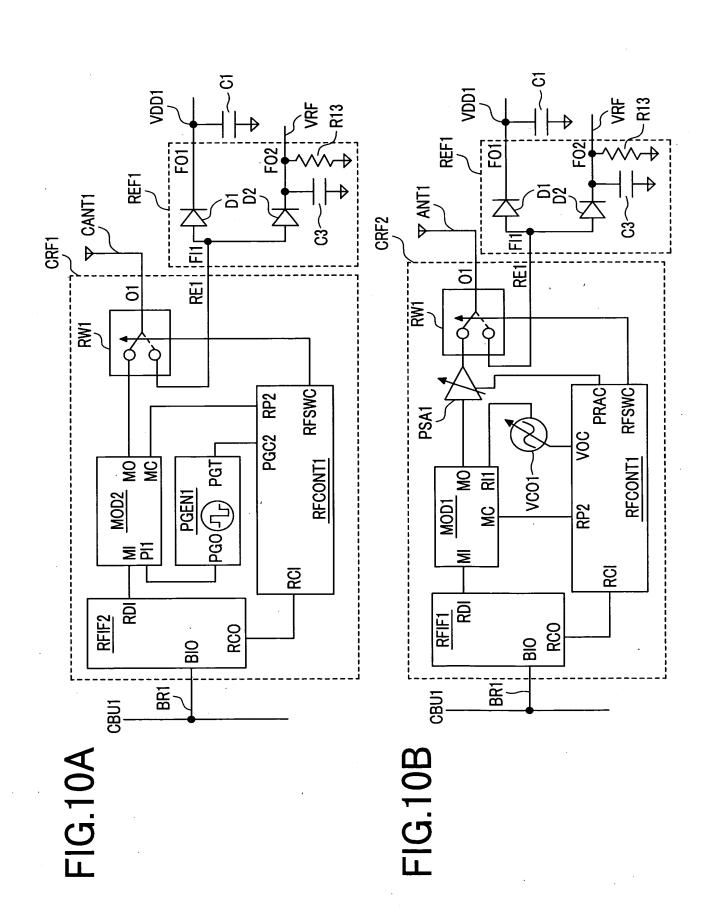


FIG.12

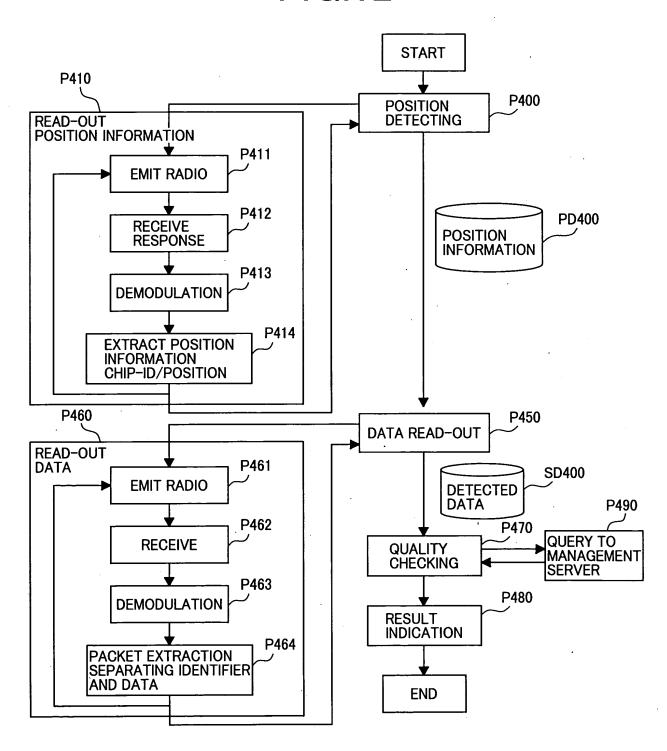


FIG.13

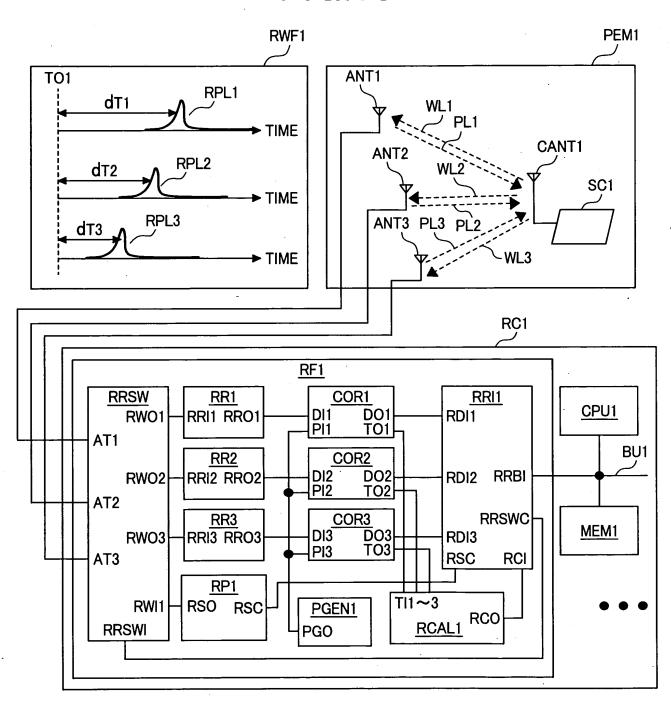


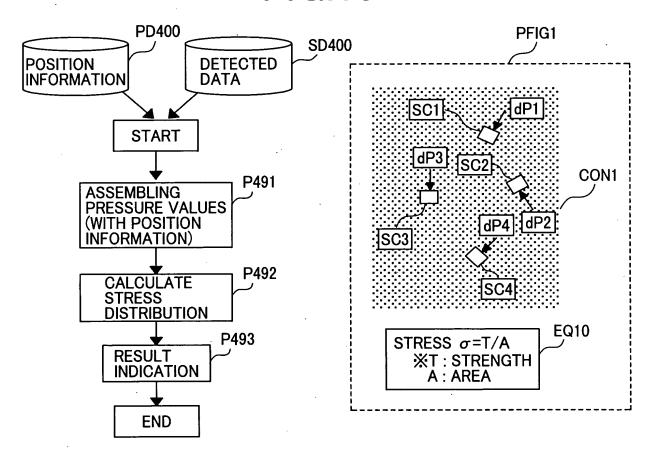
FIG.14A

	CHIP-ID	DISTANCE	DIRECTION	
	#1	0.5m	+90 , −30°	DD 400
	#2	0.7m	+15 , −15°	PD400
	#3	0.1m	−50 , +32°	<u> </u>
• [#4	0.2m	−30 , +75°	
	•	•	•	
ı	•	•	•	
١	•	•	•	

FIG.14B

DETEC	TED DATA
1.0	×10 ⁻⁹
2.1	×10 ¹ SD400
3.5	× 10 ¹
3.5	× 10 ¹
	•
	•
	•

FIG.15



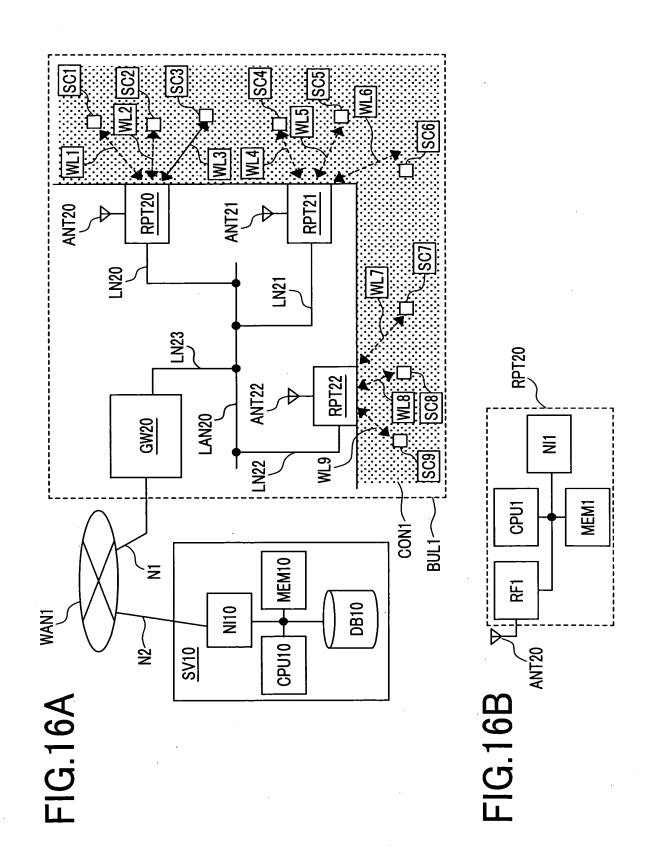
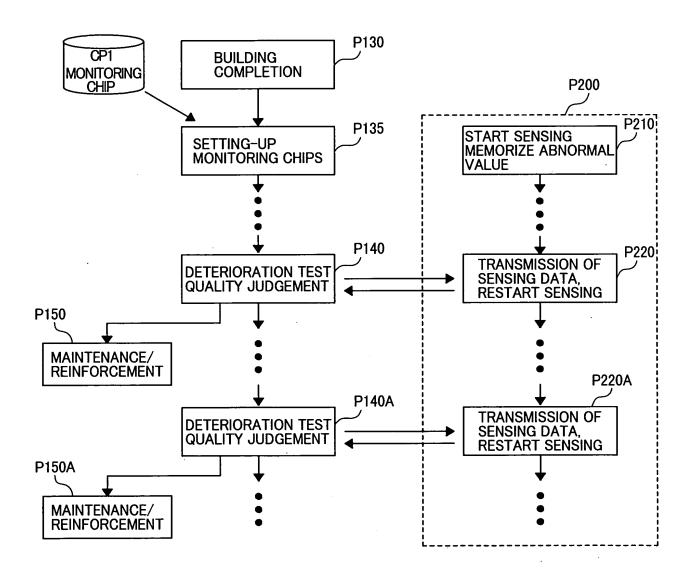


FIG.17



ANT1 HL1 문 HDD1 RF1 HL6 FIG.18 CPU1 **MEM1** 15<u>1</u> DISP1 \equiv HL7 Ξ 8 CONI BUL1 MEM10 E **DB10** N 10 WAN1 CPU10 SV10 Š

SC4

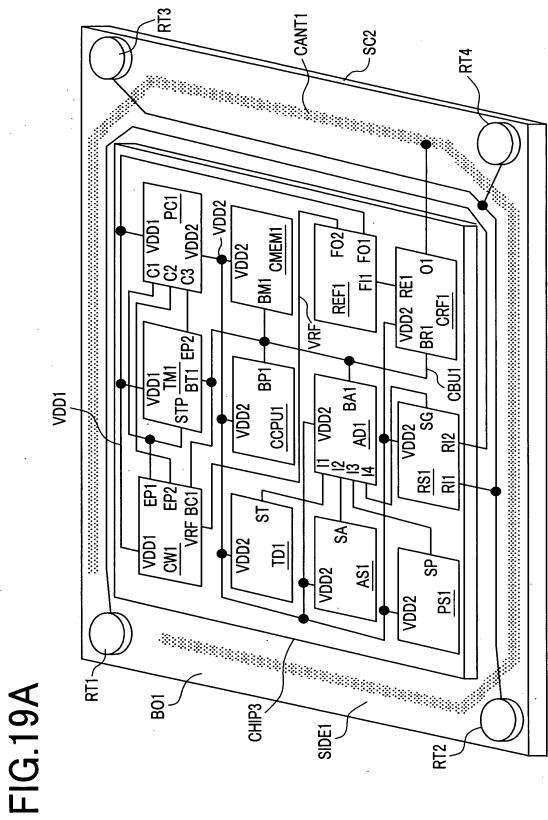


FIG.19B

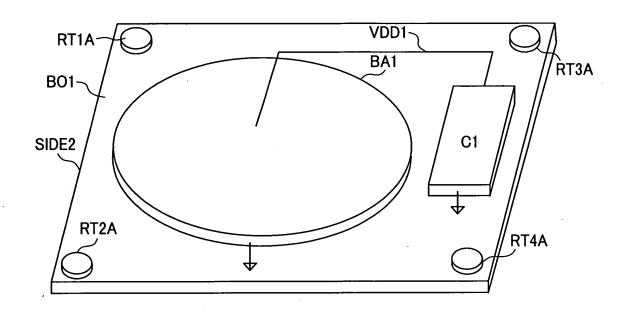


FIG.19C

